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# Properties and Corrosion Resistance of CrN/Al 5083 Coatings **The Effect of Substrate Temperature and Biasing on Physical-**

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#### **ABSTRACT**

Aluminum alloys such as Al 5083 have primary potential for lightweight structural application in automotive and aerospace industries. This paper addresses the mechanical and tribological properties and corrosion resistance of chromium nitride coatings deposited on Al 5083 that can be used for development of applications of aluminum 5083 alloy. The CrN coatings of 1 µm thickness were deposited by DC reactive magnetron sputtering technique on the Aluminum 5083 wafers at different substrate temperatures (RT and 200°C) and bias voltages (-200 and -400 V). A FESEM instrument was used for study of chemical composition, and cross-section and surface imaging. The surface physical morphology of samples was also investigated by an atomic force microscope. The mechanical and tribological properties of the films were measured by nano-indentation and scratch tests, respectively. The electrochemical behaviorand corrosion resistance of the samples were examined in NaCl (3.5%) solution using potentiodynamicmethod. The results showed that the chromium nitride coatingscaused improvementof AI 5083 properties. The results also showed the best mechanical and tribological properties and corrosion resistance for deposited coating at room temperature and -400 V bias substrate voltage. The morphological studies demonstrated that these behaviors were due to the smooth surface with compact and small grains.

Keyword: CrN; Al 5083; Bias voltage; Substrate temperature; Hardness; Corrosion resistance.

## **1. INTRODUCTION**

In the last years, some researchers have been reported ies, tip truck bodies, military vehicles, mine skips and loy is widely used in shipbuilding, rail cars, vehicle bodon the study of aluminum 5083 alloy  $[1-5]$ . Al 5083 alcages, pressure vessels due to high strength to weight ratio, reasonable corrosion resistanceand super-elastic-

in the same set of the s tant to attack by both seawater and industrial chemical extreme environments. Al 5083 alloy is highly resisenvironments. It also retains exceptional strength after welding [8]. These adequate properties of Al 5083 can be improved by hard coatings such as CrN. Because

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cal properties, such as high hardness, good corrosion of its desirable mechanical, tribological and chemiand wear resistance and thermal stability, Chromium nitride has been widely used as industrial coatings [9-13]. Prior, many researchers have been reported on mium nitrite thin films/coatings deposited by various ties  $[9-11]$  and corrosion behavior  $[12, 13]$  of chroinvestigation of mechanical and tribological properphysical methods including sputtering, cathodic arc and electron beam evaporation on different substrates. The aim of this work is to study the mechanical and tribological properties and corrosion behavior of CrN velopment of applications of aluminum 5083 alloy. sputter coated on Al 5083 that can be used for de-Therefore, we have deposited the CrN coatings by ent substrate temperatures and biasing voltages on Al DC reactive magnetron sputtering technique at differ-5083 wafer and studied the dependence of mentioned properties, chemical composition and surface morphology of coatings on deposition parameters.

## **2. EXPERIMENTAL DETAILS**

#### *deposition Coatings 2.1.*

An aluminum 5083 wafer (Wt.%, 0.02 Cu, 0.18 Si, 0.28 Fe, 0.1 Cr, 0.66 Mn, 4.1 Mg, balance Al) with di-<br>mensions of  $20\times20$  mm<sup>2</sup> was used as a substrate. The  $0.28$  Fe,  $0.1$  Cr,  $0.66$  Mn,  $4.1$  Mg, balance Al) with disubstrates were cleaned successively by acetone and nique with a commercial chromium target (of 99.99%) ings were deposited by DC magnetron sputtering techethanol, and then dry by argon flow. The Cr-N coatpure, 76 mm diameter and 1 mm thickness). Prior to strates were cleaned by Cr ion bombardment, which the deposition of chromium nitride coatings, the subsion of the deposited films. A Cr interlayer with 1um would remove contaminants and ensure good adhenitride bonding and to reduce stresses. The distance thickness was introduced to provide critical metal-tobetween the target and the substrate was maintained at  $10 \text{ cm}$ .

The thickness and deposition rate of these chromium nitride coatings were checked in situ using a quartz crystal monitor (6 MHz gold, Inficon Company, USA) cess. The thickness of the coatings was also checked located near the substrate during the sputtering pro-



**Figure 1:** SEM cross-section micrograph of selected sample (sample # II).

with FESEM cross-section images (Figure 1). The thickness was  $1\pm 0.01$  µm for all coatings. However, it should be noted that CrN coating is characterized mits the deposition of much larger thicknesses than by its fine grained and low stress structure, which perconventional PVD coatings of a few  $\mu$ m. In various applications, even  $10-25 \mu m$ -thick CrN coatings were used  $[11]$ .

sion pump, which is vertically fixed to the chamber, The vacuum chamber was equipped with a diffutimate vacuum of  $1\times10^{-6}$  mbar. After achieving the backed by a rotary pump, and could produce an ulultimate vacuum, the chamber was filled with pure argon and nitrogen gas up to required working gas pressures. The argon and nitrogen gases flow rate was kept constant at  $15$  and  $10$  sccm during the sputtering processes, respectively. The flow rates of both argon and nitrogen gases were controlled individually by perature and  $200^{\circ}$ C) and biasing voltages (-200 V and ited under various substrate temperatures (room temmass flow controllers. The Cr-N coatings were depos- $-400$  V) (details specified in Table 1).

### *characterization Coatings 2.2.*

A Hysitron Inc. Tribo Scope Nanomechanical Test Instrument with 2D transducer, complete software chanical and tribological tests and surface imaging. and Berkovich diamond indenter was used for me-



#### **Table 1:** Detail of deposition parameters

In nano-indentation test, force, loading time, dwelling time, and unloading time were  $600 \mu N$ , 30 s, 10 s and 30 s, respectively. Over 4 indentation tests were performed on all samples, and average of obtained data was presented. The distance between two indentations was not less than three times the minor diagonal to prevent stress-field effects from nearby indentations. In scratch test, force, scratch length and scratch time were 600  $\mu$ N, 4  $\mu$ m and 35 s, respectively. The AFM analysis was carried out using a NanoScope E from Digital Instruments, USA. The scan size and scan rate were 5×5  $\mu$ m<sup>2</sup> and 1.001 Hz, respectively. Surface images, roughness parameters, nano hardness, scratch volume and friction coefficient were obtained from

these analyses. A Scanning Electron Microscope SEM (model: CamScan MV2300, Czech & England) was also employed for study of chemical composition and surface physical morphology.

2.3. Electrochemical/corrosion behavior of coatings der to carry out this analysis only anarea of  $1.0\pm 0.05$ tiostat coupled to PC  $(273A, EG&G, Ireland)$ . In orined using the potentiodynamic method with a poten-Electrochemical behavior of the samples was exam- $\text{cm}^2$  was exposed to the NaCl (3.5%) solution. A satu num counter electrode were used in three electrode rated calomel reference electrode (SCE) and a platisetup. Samples were polarized from -250 mV versus



*Figure 2: 2D and 3D AFM images of selected samples, a) sample # I and b) sample # III.* 

Sample	Substrate bias V	Substrate temp. ${}^{\circ}C)$	Grain size (nm)	Roughness $rms(\AA)$
	$-200$	<b>RT</b>	75	55
П	$-400$	<b>RT</b>	43	32
Ш	$-200$	200	102	82
ſV	$-400$	200	54	

**Table 2:** Detail of atomic force microscopy analysis

open circuit potential at a scan rate of  $0.8 \text{ mV s}^{-1}$ . The potential scan began after a stabilization period of sidering transpassive behavior in polarization curves. 15 min. The end of the scans was selected after con-All of the potentials presented in this work are as a function of SCE

## **3. RESULTS AND DISCUSSION**

### 3.1. AFM analysis

ples  $#$  I and III) are shown in Figure 2, while the grain 2D and 3D AFM images of selected samples (samsize (obtained from 2D AFM images by JMicrovision code) and surface roughness values for all samplesare given in Table 2. The results showeda smooth surface withsmall and compact grains for deposited coating at the room temperature and  $-400$  V biasing voltage ture. In addition, the images show that the surface ness increased with increasing of substrate tempera-(sample  $\#$  II), while the grains size and surface roughis porous and the individual crystallites are clearly separated from one another for deposited samples at -200 V bias voltages (i.e. samples  $#$  I and III). At low substrate temperature where the mobility of adatoms is limited by substrate temperature, atoms arriving on the substrate surface for lower deposition rate have just sufficient time and mobility to move and coalesce with each other, or with existing larger grains. For a much higher deposition rate, as soon as the first atom barded by incoming atoms and become buried under is deposited on the substrate surface it will be bomthese atoms with a significant reduction in its mobility. therefore numerous small new nuclei and small grains are produced on the surface of the substrate [14]. According to this preamble and as can be seen in Table ple II are related to higher deposition rate and lack of 1, smaller gains and lower surface roughness of samever, it will be expected that increasing of negative mobility due to the low substrate temperature. Howbias voltage to higher values may causesan increasein grains size and a porous structure due to addition ment. Higher biases can also result in re-sputtering. energy of adatoms which obtained from ion bombardeffects and stoichiometry changes because of preferential removal of the relatively light nitrogen atoms from the coating.

### *analyses SEM and EDAX 3.2.*

The N/Cr ratio (i.e. x in CrN<sub>x</sub>) of the chromium ni tride coatings was deduced with energy dispersive X-ray (EDAX) measurements. This ratio didn't show the significant changes with substrate temperature and biasing and was almost constant (i.e. $0.96\pm0.02$ ) for all samples. There are two known crystalline chromium nitride including CrN and  $Cr_2N$ , and above mentioned stoichiometry indicates that all our samples have CrN structure. In addition to atomic force microscopy, we have used scanning electron microscopy for surface



**Figure 3: Values of hardness of CrN coatings deposited** on AI 5083 at different substrate temperatures and biasing *.voltages*



**Figure 4:** 2D and 3D AFM images of selected samples (sample # II) after nano-indentation test.

graphs of CrN coatings didn't provide any more infor-<br>mation than the AFM images. and cross-section imaging of the films. SEM micro-<br>graphs of CrN coatings didn't provide any more infor-

## **3.3. Nano-indentation test**

CrN hard coatings are widely used due to their excellent mechanical properties that make them useful in a wide variety of industrial applications. Figure 3 shows values of CrN coatings hardness prepared in this work. 2D and 3D AFM images of selected samples (sample ure 4. It can be seen that the deposited film at higher  $#$  II) after nano-indentation test are also shown in Figbiasing voltage  $(-400 \text{ V})$  and room temperature (i.e. sample  $#$  II) shows the maximum value of hardness  $(21.9 \text{ GPa})$ . The results also show that the hardness decreases with deposition at  $-200$  V and increasing of substrate temperature to 200°C. Hardness is complex quantity which affected by different parameters. There are many results in the literature regarding the effective parameters on hardness of thin films/coat-



**Figure 5:** Values of friction coefficient of CrN coatings *deposited on AI 5083 at different substrate temperatures* and biasing voltages.

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ings such as atomic bonding [15], microstructure [16],<br>
stress/strain [17], texture [18], crystallographic ori-<br>
entation and structure [19, 20] and so on. Some ex-<br>
perimental results also indicate that film hardness perimental results also indicate that film hardness and entation and structure  $[19, 20]$  and so on. Some exstress/strain [17], texture [18], crystallographic orisurface roughness have an inverse relation [21], so that the films with more surface roughness may possibly have an open and porous structure, which leads to lower hardness. Furthermore, in previous work, we have showed that denser structures consisting of small grains and more grain boundaries result in more values of hardness [22].

The hardness of our CrN samples can be affected by all above mentioned parameters. But according to ited sample at room temperature and -400 V bias voltages<br>can be attributed to the denser structure of these our structural analyses, the higher hardness of deposited sample at room temperature and -400 V bias voltfilm namely small grains with more grain boundaries and lower surface roughness. However, an increase in substrate temperature to  $200^{\circ}$ C or a change in biasing voltage to -200 V cause larger grains with more grain



**Figure 6:** Values of scratch volume of CrN coatings deposited on AI 5083 at different substrate temperatures and biasing voltages.



**Figure 7:** 2D and 3D AFM images of selected samples (sample # II) after scratch test.

boundaries and surface roughness which in turn result in porous structure.

## 3.4. Scratch test

The values of friction coefficient and scratch volume tures and biasing voltages are shown in Figures 5 of all samples deposited at various substrate temperaand 6, respectively. The results showed the minimum value of friction coefficient and scratch volume for sample II, while the mentioned parameters increased with increasing of substrate temperature and change of substrate voltage to -200 V.

ed by a number of factors such as films density and The tribological properties of coatings can be affectmicrostructure, size of grain, residual stresses as well as the interfacial surface between the substrate and the coating [23]. These factors are related to the methods



ings deposited on AI 5083 at different substrate tempera-<br>tures and biasing voltages. **Figure 8:** Potentiodynamic polarization curves of CrN coat-<br>ings deposited on AI 5083 at different substrate tempera-**Figure 8:** Potentiodynamic polarization curves of CrN coat-

and parameters of coatings deposition. In our previous work [22], we have showed that coefficient of friction pography. On the other hand, harder coatings (namely structure and had no direct relation to their surface toand scratch volume depended mainly on films microsample  $\#\text{II}$ ) with denser structure presents the lower friction coefficient and scratch volume. Subsequently, by an increase in substrate temperature or change of bias voltage due to the increasing of grains size and surface roughness the mentioned parameters decrease. Figure 7 shows the 2D and 3D AFM images of selected sample (sample  $#$  II) after scratch test.

#### *behavior Corrosion 3.5.*

In spite of its excellent mechanical and tribological properties, Al 5083 corrosion resistance has always fects such as pores and pinholes which are resulted of been conditioned by the presence of structural dedeposition parameters and methods, and cracks that appear during application  $[24-26]$ . The corrosion resistance of Al 5083 can be improved with suitable coatings such as Chromium nitride.

ings prepared in this work was checked in NaCl The corrosion behavior of chromium nitride coat-(3.5%) solution. The Potentiodynamic polarization curves of CrN coatings deposited on Al 5083 are shown in Figure 8. The curves describe a wide passive stage, and then a breakdown potential. This behavior was also observed in previous works for CrN coatings which deposited on different substrates ization curves are also given in Table 3. The results  $[27, 28]$ . The numerical data obtained from polar-(column 4 of Table 3) show the lowest corrosion cur-

Sample	Substrate	Substrate	Corrosion	Corrosion	Passive
	bias	temperature	current density	potential	current density
	(V)	$(^{\circ}C)$	$(\mu A.cm^{-2})$	(mV vs. SCE)	$(\mu A.cm^{-2})$
	$-200$	<b>RT</b>	0.10	$-52$	0.30
П	$-400$	<b>RT</b>	0.01	$-125$	0.08
Ш	$-200$	200	0.20	$-67$	0.70
IV	$-400$	200	0.08	$-97$	0.12

**Table 3: Detail of electrochemical characteristics of CrN /AI 5083 coatings.** 

ture and  $-400$  V (sample  $\#$  II). The corrosion current rent density for deposited sample at room temperadensity is often used as an important parameter to rosion current density measured via polarization sion protection is normally proportional to the corevaluate the kinetics of corrosion reactions. Corro-[28]. Comparing the other parameters of Table 3 also sion resistance. However, the resistance decreases demonstrate that sample II shows the highest corrowith change of substrate bias voltage to  $-200$  V and substrate temperature to  $200^{\circ}$ C. This behavior can be attributed to variation of surface morphology with deposition parameters as mentioned in section  $3.1$ . It can be seen in AFM result analysis that sample rous structure and surface roughness increased with pact grains. Furthermore, the surface found the po-II showed a smooth surface with small and comstrate temperature to  $200^{\circ}$ C due to the formation of change of substrate bias voltage to  $-200$  V and sublarger grains and appearance of grooves in the film. Both of these effects are related to each other and result in larger surface area (effective surface) being exposed to the corroding environment while it is also expected that the film become thinner in the grooves. Therefore, higher rate of corrosion reactions between these increased surface areas and the corroding solution is expected.

## **CONCLUSIONS 4.**

erties and corrosion resistance of CrN/Al 5083 sput-<br>tered-coatings on substrate temperature and biasing The dependence of mechanical and tribological properties and corrosion resistance of CrN/Al 5083 sputvoltage is studied. Investigation of chemical composi-

tion obtained from EDAX analysis showed that the<br>
at different conditions. The surface morphology of<br>
and different conditions. The surface morphology of<br>
samples was studied by AFM and FESEM. These<br>
results showed that t ratio of N/Cr was  $0.96\pm0.02$  for all samples prepared at different conditions. The surface morphology of samples was studied by AFM and FESEM. These results showed that the change of substrate bias form ture from RT to  $200^{\circ}$ C caused increasing of grains size  $-400$  V to  $-200$  V and increasing of substrate temperaand surface roughness. The results showed the higher hardness and corrosion resistance, and lower friction coefficient and scratch volume for deposited coatings tions demonstrated that these behaviors were due to ture than the other coatings. The structural investigaat -400 V substrate bias voltage and room temperathes mooth surfaces with small and compact grains of mentioned coatings relative to porous and rough surface of other samples.

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